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(12) **United States Design Patent** (10) **Patent No.:** **US D934,991 S**
Amano et al. (45) **Date of Patent:** **** Nov. 2, 2021**

(54) **COMPONENT OF A LIQUID DISCHARGE NOZZLE FOR SEMICONDUCTOR SUBSTRATE PROCESSING APPARATUS**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **23-01**

(52) **U.S. Cl.**
USPC **D23/213**

(58) **Field of Classification Search**
USPC D23/213, 214, 215, 223, 224, 226, 229
CPC A61H 9/0021; A61H 33/00; B05B 1/00; B05B 1/14; B05B 1/185; B05B 1/08; B05B 1/02; B05B 1/26; B05B 12/002; B05B 1/18; B05B 9/01
See application file for complete search history.

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(57) **CLAIM**

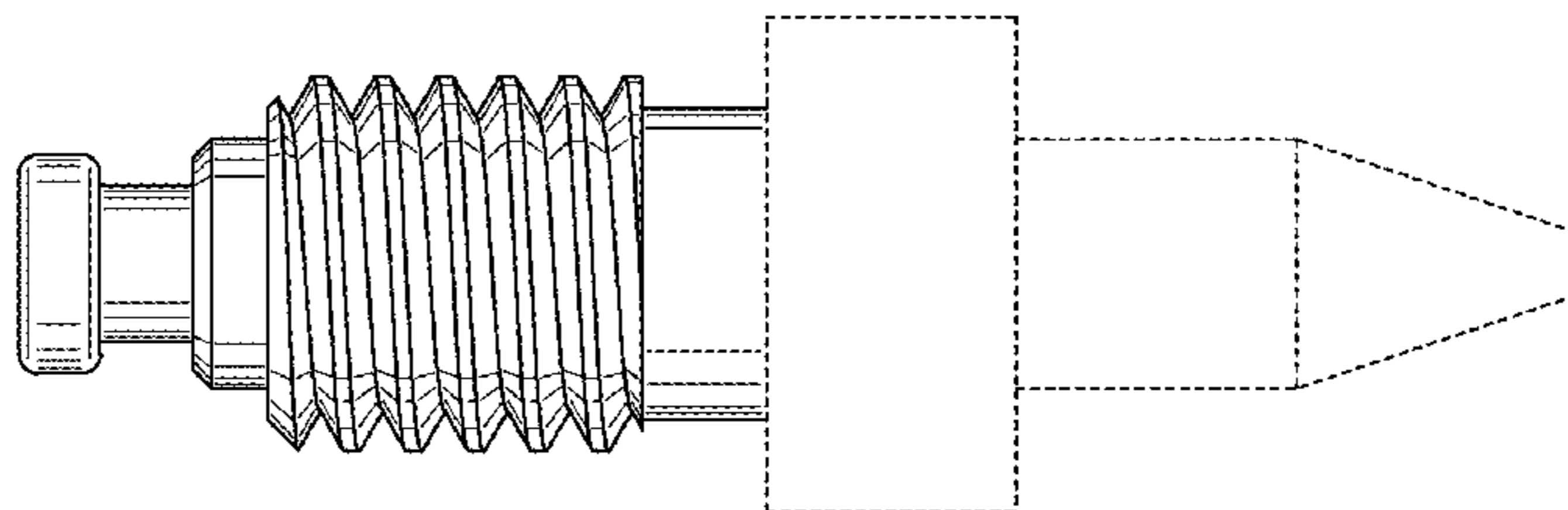
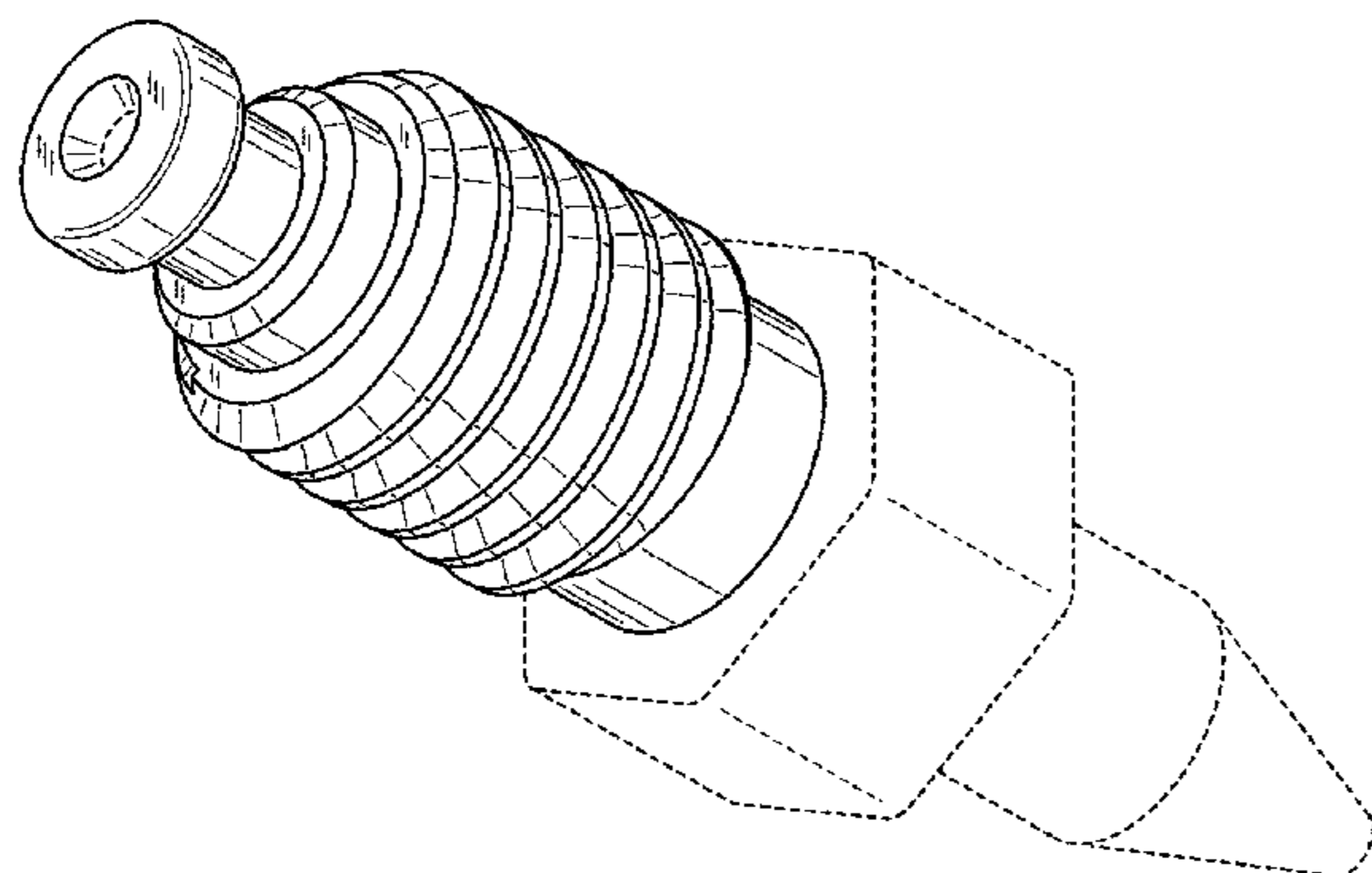
The ornamental design for a component of a liquid discharge nozzle for semiconductor substrate processing apparatus, as shown and described herein.

DESCRIPTION

FIG. 1 is a front, bottom and left-side perspective view of a component of a liquid discharge nozzle for semiconductor substrate processing apparatus;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left-side elevational view thereof;
FIG. 5 is a right-side elevational view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

The broken lines shown represent portions of a component of a liquid discharge nozzle for semiconductor substrate processing apparatus and form no part of the claimed design.

1 Claim, 4 Drawing Sheets



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FIG. 1

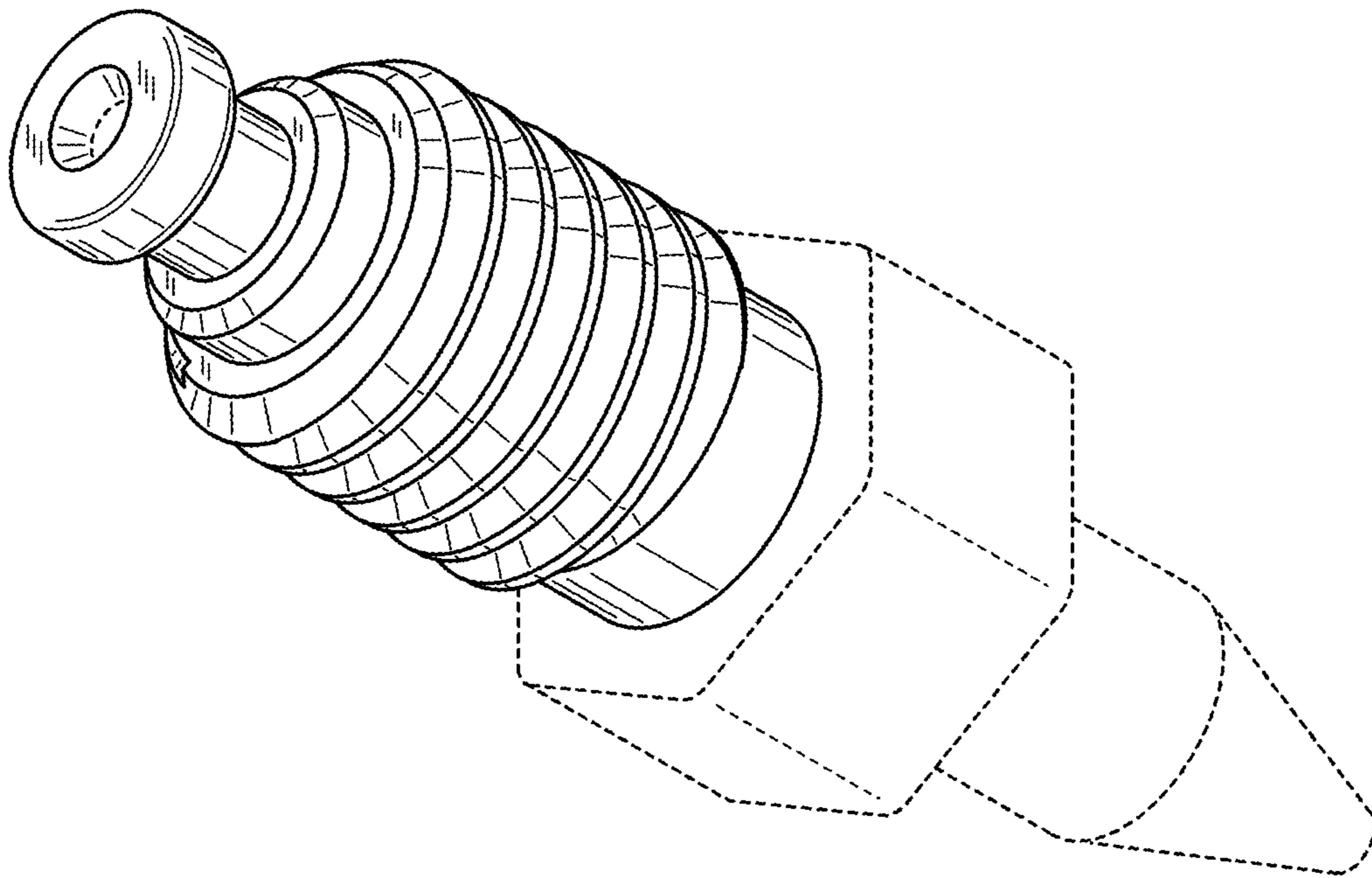


FIG. 2

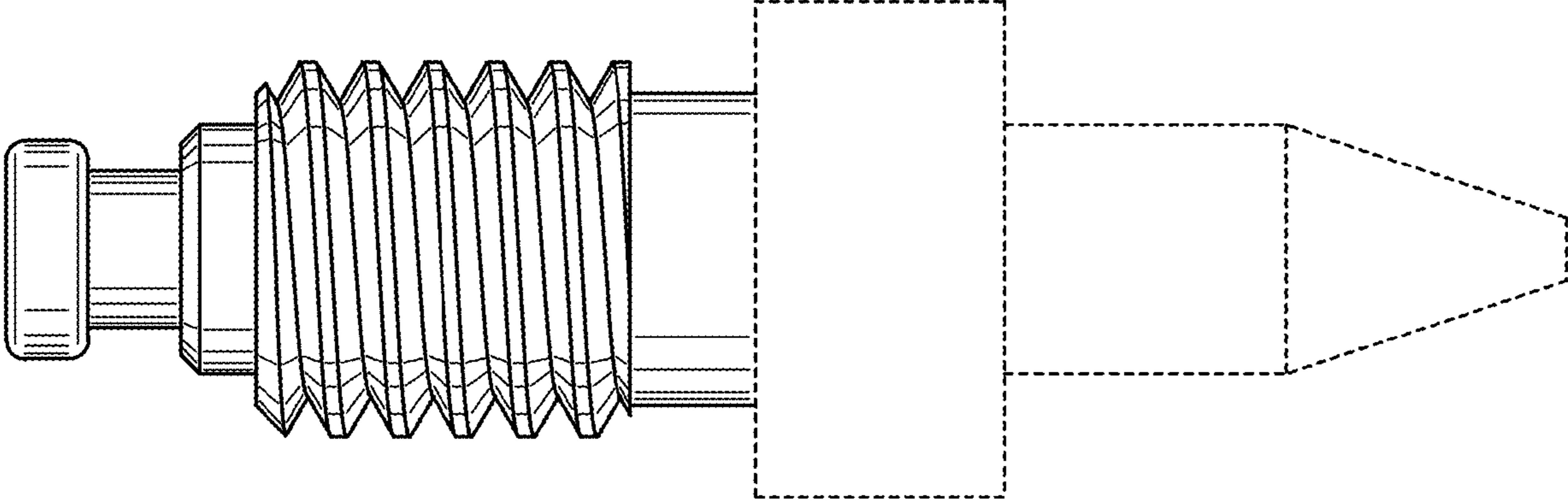


FIG. 3

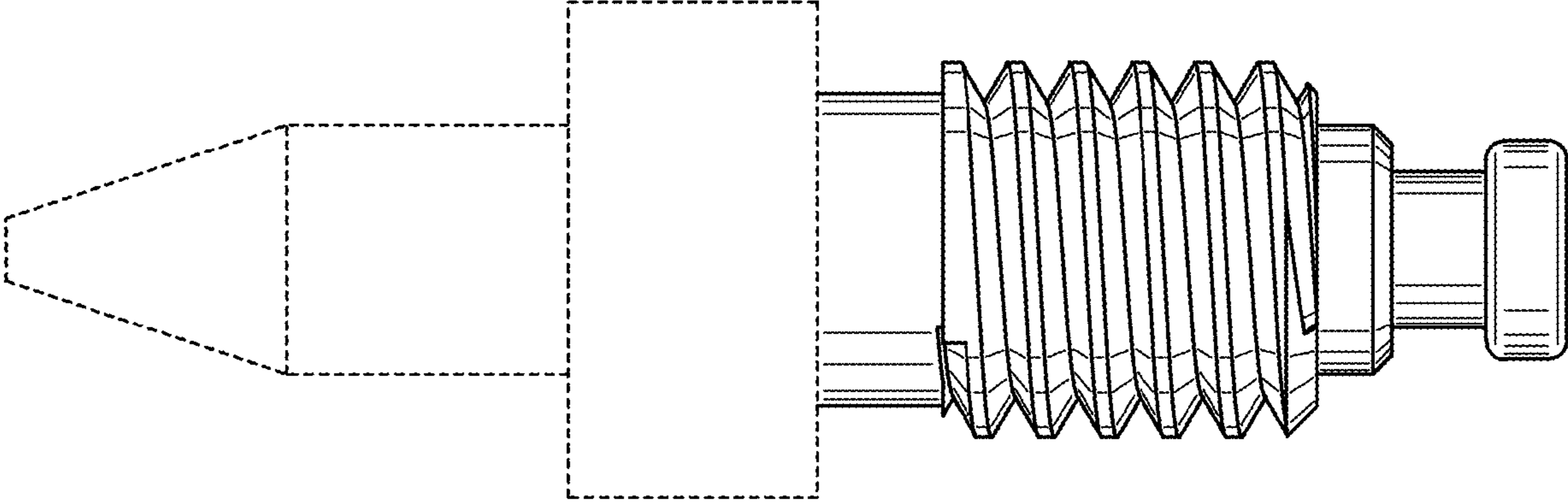


FIG. 4

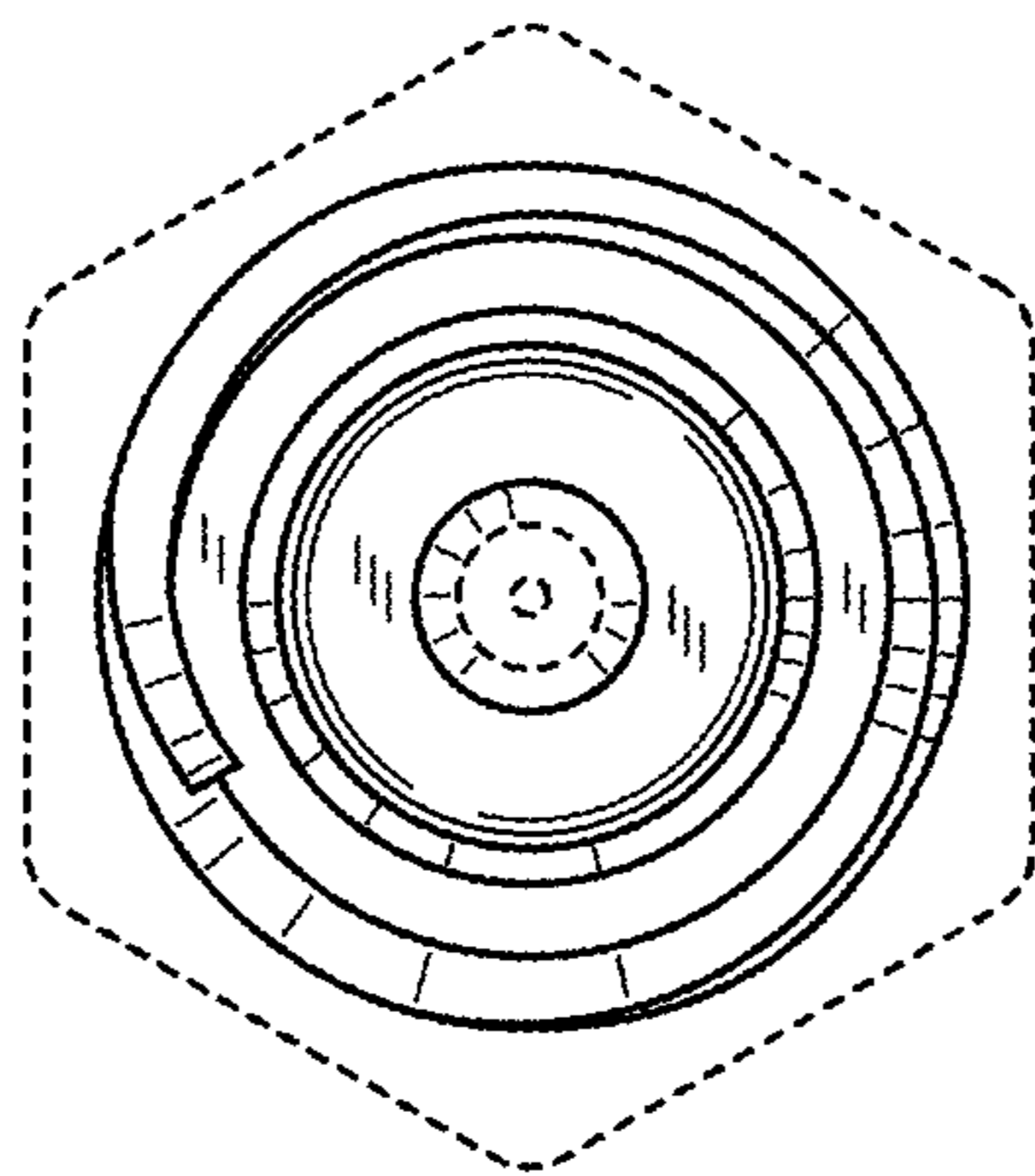


FIG. 5

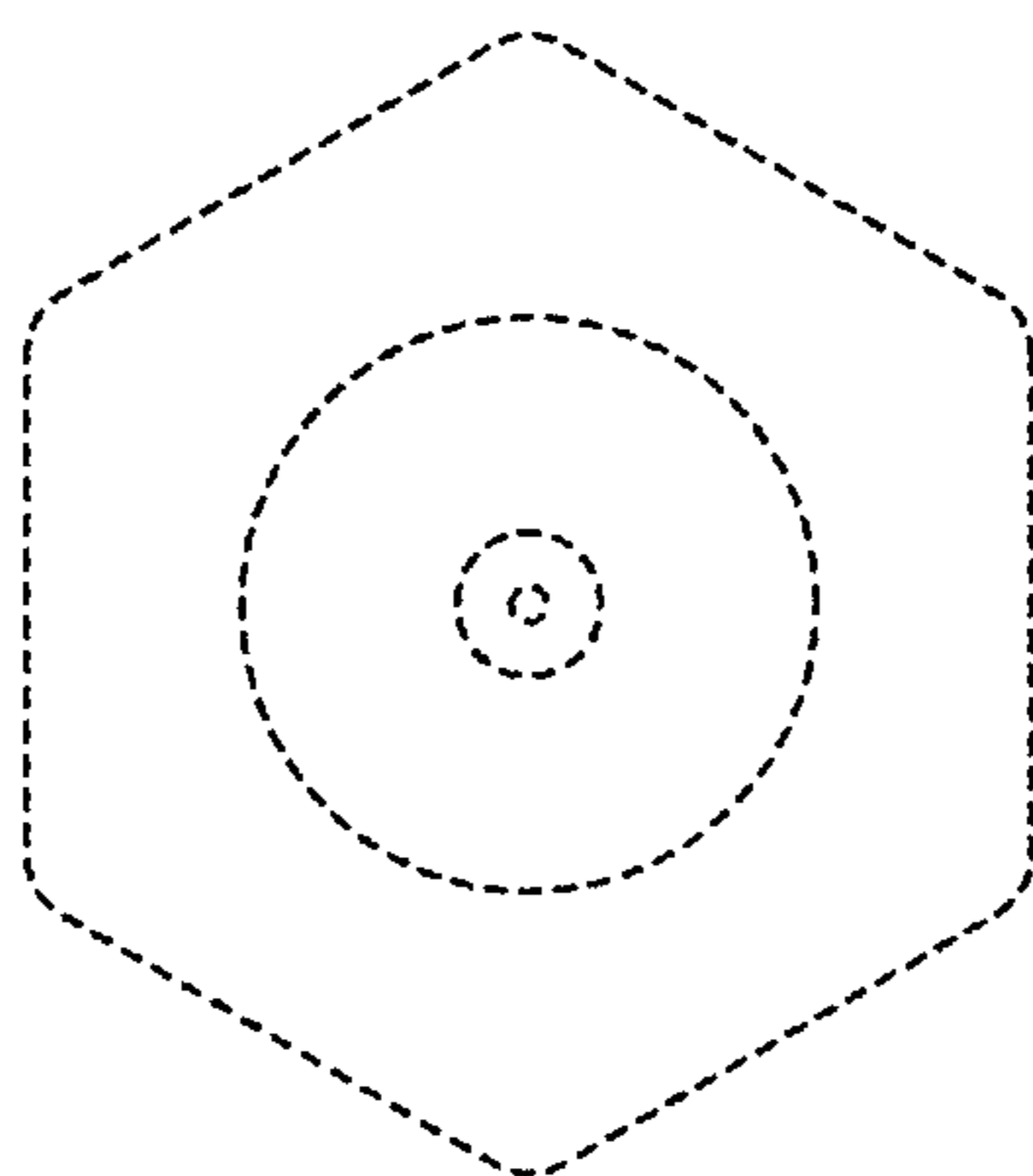


FIG. 6

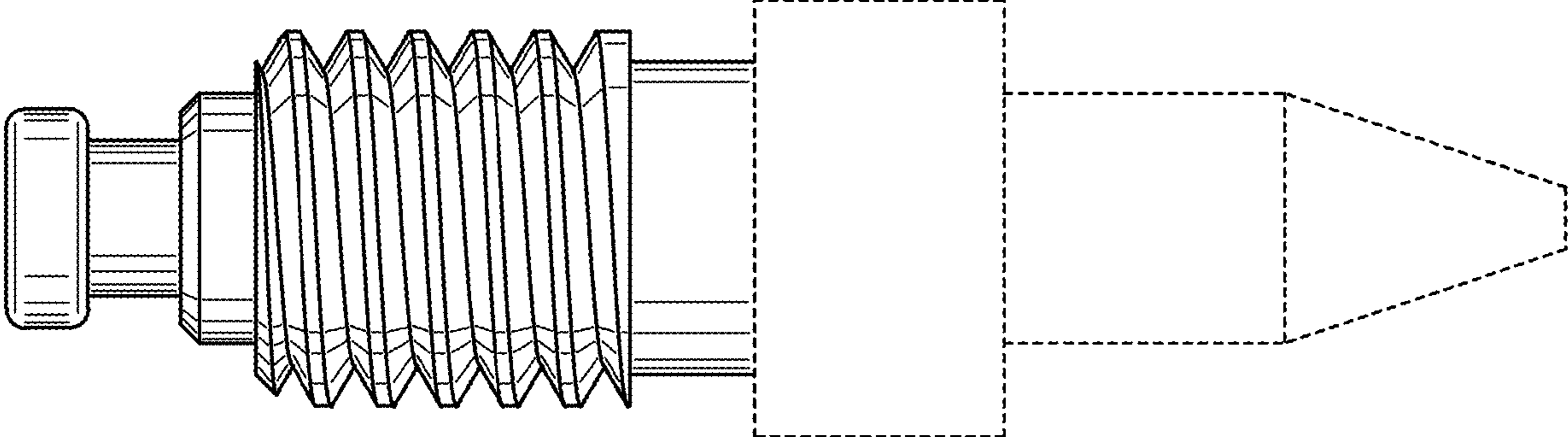


FIG. 7

